

2806A-VB TO247 Datasheet N-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	60			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.0028			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.004			
I _D (A)	210			
Configuration	Single			

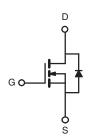
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- Package with Low Thermal Resistance
- \bullet 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC









N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage	V_{DS}	60	V		
Gate-Source Voltage	V _{GS}	± 20	V		
Continuous Drain Current	T _C = 25 °C	,	210		
	T _C = 125 °C	l _D	120 ^a		
Continuous Source Current (Diode Conduct	I _S	120 ^a	Α		
Pulsed Drain Current ^b	I _{DM}	480			
Single Pulse Avalanche Current	1 0411	I _{AS}	75		
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	281	mJ	
Maximum Power Dissipation ^b	T _C = 25 °C	P _D	375	10/	
	T _C = 125 °C		125	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to + 175	°C	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount ^c	R_{thJA}	40	°C/W
Junction-to-Case (Drain)		R_{thJC}	0.4	C/ VV

Notes

- a. Package limited.
- b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- c. When mounted on 1" square PCB (FR-4 material).
- d. Parametric verification ongoing.

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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static	1			ı				
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0$, $I_D = 250 \mu A$		60	-	-	V	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_D = 250 \mu A$		2.0	2.5	V	
Gate-Source Leakage	I _{GSS}	V _{DS} =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 100	nA	
		V _{GS} = 0 V	V _{DS} = 60 V	-	-	1.0		
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V	V _{DS} = 60 V, T _J = 125 °C	-	-	50	μΑ	
		V _{GS} = 0 V	V _{DS} = 60 V, T _J = 175 °C	-	-	350		
On-State Drain Current ^a	I _{D(on)}	V _{GS} = 10 V	$V_{DS} \ge 5 V$	120	-	-	Α	
		V _{GS} = 10 V	I _D = 30 A	-	0.0028	-	Ω	
Drain Course On State Resistance	В	V _{GS} = 10 V	I _D = 30 A, T _J = 125 °C	-	0.0060	-		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V	I _D = 30 A, T _J = 175 °C	-	0.0080	-		
		V _{GS} = 4.5 V	I _D = 20 A	-	0.004	-		
Forward Transconductanceb	9 _{fs}	V _{DS} = 15 V, I _D = 30 A		-	109	-	S	
Dynamic ^b								
Input Capacitance	C _{iss}			-	7300	9125	pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 V$	V _{DS} = 25 V, f = 1 MHz	-	935	1170		
Reverse Transfer Capacitance	C _{rss}	1		-	647	810		
Total Gate Charge ^c	Qg			-	184	276		
Gate-Source Charge ^c	Q _{gs}	V _{GS} = 10 V	$V_{DS} = 30 \text{ V}, I_{D} = 110 \text{ A}$	-	24.7	-	nC	
Gate-Drain Charge ^c	Q _{gd}]		-	50.4	=-		
Gate Resistance	R _g	f = 1 MHz		0.5	1.1	1.6	Ω	
Turn-On Delay Time ^c	t _{d(on)}				19	29		
Rise Time ^c	t _r	$V_{DD} = 30 \text{ V}, \text{ R}_L = 0.27 \Omega$ $I_D \cong 110 \text{ A}, \text{ V}_{GEN} = 10 \text{ V}, \text{ R}_g = 2.5 \Omega$		-	23	35	ns	
Turn-Off Delay Time ^c	t _{d(off)}			-	83	125		
Fall Time ^c	t _f			-	35	53		
Source-Drain Diode Ratings and Char	acteristics ^b							
Pulsed Current ^a	I _{SM}			-	-	480	Α	
Forward Voltage	V _{SD}	I _F =	-	0.9	1.5	V		

Notes

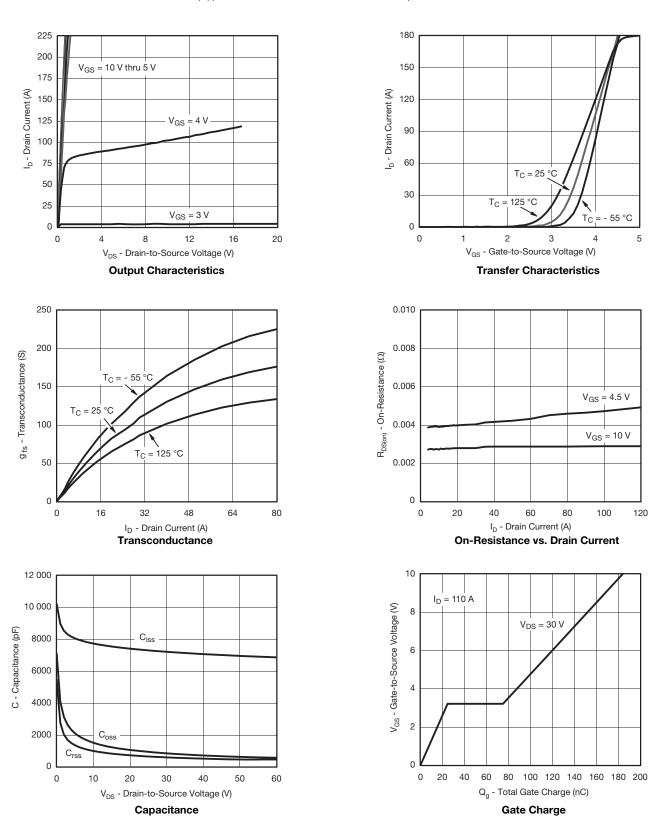
- a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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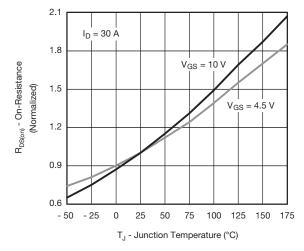


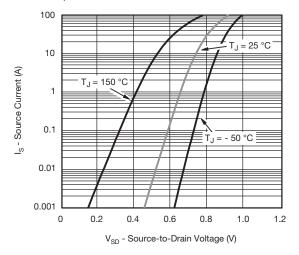
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



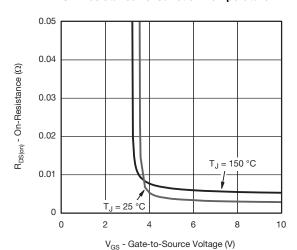


TYPICAL CHARACTERISTICS ($T_A = 25 \, ^{\circ}\text{C}$, unless otherwise noted)

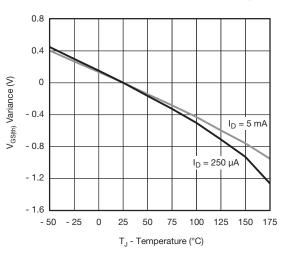




On-Resistance vs. Junction Temperature



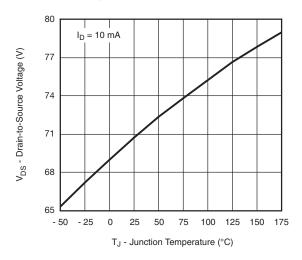
Source Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage

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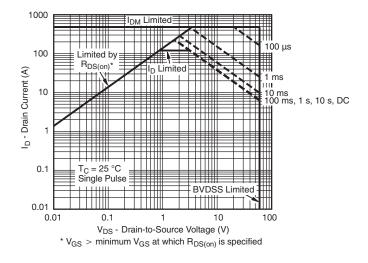




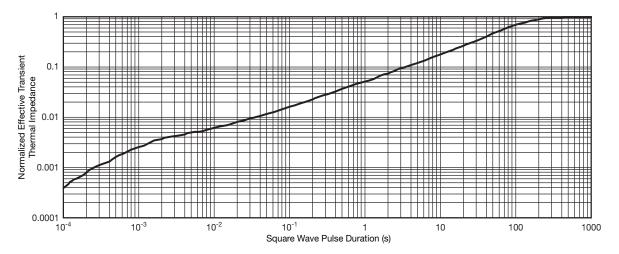
Drain Source Breakdown vs. Junction Temperature



THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)



Safe Operating Area



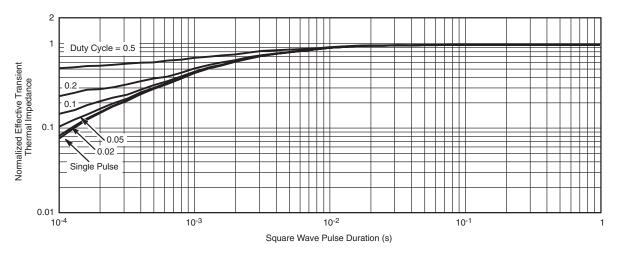
Normalized Thermal Transient Impedance, Junction-to-Ambient

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THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

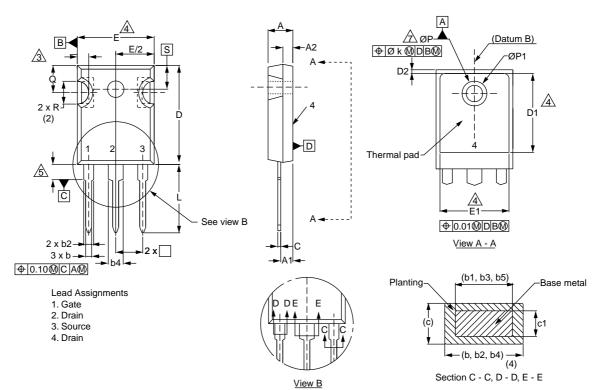
can widely vary depending on actual application parameters and operating conditions.

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities

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TO-247AC



	MILLIM	IETERS	INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
Α	4.58	5.31	0.180	0.209
A1	2.21	2.59	0.087	0.102
A2	1.17	2.49	0.046	0.098
b	0.99	1.40	0.039	0.055
b1	0.99	1.35	0.039	0.053
b2	1.53	2.39	0.060	0.094
b3	1.65	2.37	0.065	0.093
b4	2.42	3.43	0.095	0.135
b5	2.59	3.38	0.102	0.133
С	0.38	0.86	0.015	0.034
c1	0.38	0.76	0.015	0.030
D	19.71	20.82	0.776	0.820
D1	13.08	-	0.515	-

	MILLIM	IETERS	INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
D2	0.51	1.30	0.020	0.051
E	15.29	15.87	0.602	0.625
E1	13.72	-	0.540	-
е	5.46	BSC	0.215	BSC
Ø	0.2	254	0.010	
L	14.20	16.25	0.559	0.640
L1	3.71	4.29	0.146	0.169
N	7.62 BSC		0.300 BSC	
Ø	3.51	3.66	0.138	0.144
ØΡ	-	7.39	-	0.291
Q	5.31	5.69	0.209	0.224
R	4.52	5.49	0.178	0.216
S	5.51	BSC	0.217	BSC

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